



Material Content Data Sheet



Sales Product Name		IDP2303A		Issued		19. January 2018		
MA#		MA001798478						
Package		PG-DSO-16-21		Weight*		174.76 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.971	1.13	1.13	11277	11277
leadframe	inorganic material	phosphorus	7723-14-0	0.023	0.01		130	
	non noble metal	zinc	7440-66-6	0.091	0.05		519	
	non noble metal	iron	7439-89-6	1.813	1.04		10372	
wire	non noble metal	copper	7440-50-8	73.601	42.12	43.22	421159	432180
	noble metal	palladium	7440-05-3	0.001	0.00		6	
	non noble metal	copper	7440-50-8	0.103	0.06	0.06	589	595
encapsulation	organic material	carbon black	1333-86-4	0.282	0.16		1615	
	plastics	epoxy resin	-	9.125	5.22		52217	
	inorganic material	silicondioxide	60676-86-0	84.667	48.45	53.83	484484	538316
leadfinish	non noble metal	tin	7440-31-5	1.562	0.89	0.89	8940	8940
plating	noble metal	silver	7440-22-4	0.641	0.37	0.37	3668	3668
glue	plastics	acrylic resin	-	0.193	0.11		1105	
	noble metal	silver	7440-22-4	0.685	0.39	0.50	3919	5024
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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